

FLIP CHIP BONDER

Since 1980



FLIP CHIP BONDER - A110 Ultra



High Productivity

- 15,000 UPH (Based on Dry Run)



Mass Defect Protection Capability

- Flux, Die Tilt, Ejector Pin Missing, Contamination



Precision Bonding Capability

- $\pm 5\mu\text{m}$ @ 3σ



Thin Die / Small Die Capability

- Min. 50 μm Thickness / Min. 0.5mm x 0.5mm



Semiconductor

FLIP CHIP BONDER A110 Ultra

Enhanced Machine Features

High Productivity

- 15,000 UPH (Based on Dry Run)
- Dual Bonding Head
- Hanmi Special Sequence Profile
- Enhanced Temperature Control System

Precision Bonding Capability

- $\pm 5\mu\text{m}$ @ 3σ
- Supreme Vision Inspection System
- High Accurate Gantry Structure
- Lower Vibration Control System
- One Casting Body Structure

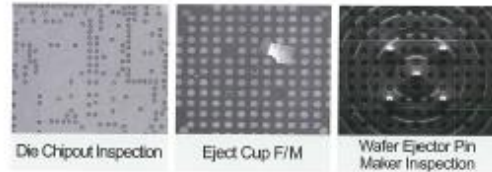
Mass Defect Protection Capability

- Hanmi Special Flux Vision Inspection System
- Auto Flatness Check System
- Wafer Map Shift Prevent Function
- Foreign Material Detect Inspection System
- Ejector Pin Missing Inspection System
- Chip Out Detect Inspection System
- Multi Reject Mark Reading Capability

User Friendly & Easy Operation

- Windows Based HMI Screen
- Easy & Quick Conversion
- Easy Maintenance

"New Technology" Flux Vision Inspection



Components and Substrates

Wafer	Die Size	0.5mm ~ 30mm
	Die Thickness	0.05mm ~ 3mm
	Wafer Size	up to 12" wafer & 15" frame
Substrate	Width	28mm ~ 208mm
	Length	50mm ~ 300mm

Performance

Productivity	UPH	15,000 (Based on Dry Run)	MTBA	2 hours
Accuracy	X-Y Placement	$\pm 5.0\mu\text{m}$ @ 3σ	MTBF	168 hours
	Chip Rotation (θ)	$\pm 0.05^\circ$ @ 3σ		
Bonding Head	Bonding Force	1N ~ 20N (Programmable from 1N)	MTTA	3 minutes
Footprint	Dimension (W x D x H)	1,600mm x 1,230mm x 1,600mm	MTTR	30 minutes
	Weight	2,600 kg		



#532-2, Gajwa-Dong, Seo-Gu, Incheon, 404-250, Korea
TEL. +82-32-571-9100 www.hanmisemi.com